

High Speed Electronics 2019 – Exercise 1 Solutions

1. a) Effective conduction band density of states of $\text{In}_{0.53}\text{Ga}_{0.47}\text{As}$ $N_c = 2.1 \cdot 10^{17}/\text{cm}^3$
 $n \approx N_d$ (Donor doping concentration)

For $N_d = 10^{16}/\text{cm}^3$,
 $n < 0.05N_c$ and the Maxwell-Boltzmann statistics holds.
 Therefore,

$$E_f - E_c = kT \ln\left(\frac{n}{N_c}\right)$$

$$= -0.08 \text{ eV}$$

For $N_d = 10^{18}/\text{cm}^3$,
 $n > 0.05N_c$ and so using Joyce-Dixon approximation,

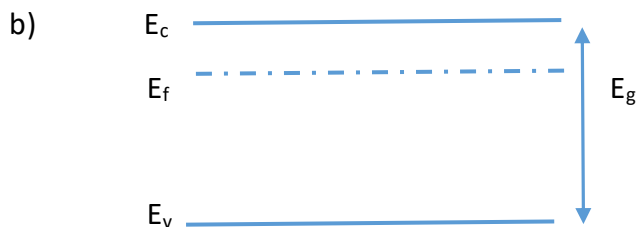
$$E_f - E_c = kT \left[\ln\left(\frac{n}{N_c}\right) + \frac{1}{\sqrt{8}} \left(\frac{n}{N_c}\right) - 0.00495 \left(\frac{n}{N_c}\right)^2 \right]$$

$$= 0.08 \text{ eV}$$

For $N_d = 10^{19}/\text{cm}^3$,
 $n > 0.05N_c$ and so using Joyce-Dixon approximation,

$$E_f - E_c = kT \left[\ln\left(\frac{n}{N_c}\right) + \frac{1}{\sqrt{8}} \left(\frac{n}{N_c}\right) - 0.00495 \left(\frac{n}{N_c}\right)^2 \right]$$

$$= 0.24 \text{ eV}$$



Number of holes

$$p = N_v e^{\frac{E_v - E_f}{kT}}$$

$$E_c - E_v + E_f - E_f = E_g$$

$$(E_v - E_f) = -E_g - (E_f - E_c)$$

Effective conduction band density of states of $\text{In}_{0.53}\text{Ga}_{0.47}\text{As}$ $N_v = 7.7 \cdot 10^{18}/\text{cm}^3$
Bandgap of $\text{In}_{0.53}\text{Ga}_{0.47}\text{As}$ $E_g = 0.74$ eV

n (/cm ³)	$E_f - E_c$ (eV)	$E_v - E_f$ (eV)	p (/cm ³)
10^{16}	-0.08	-0.66	$5.9 \cdot 10^7$
10^{18}	0.08	-0.82	$1.2 \cdot 10^5$
10^{19}	0.24	-0.98	245

c)

By mass action law,

$$n_i^2 = \left(\sqrt{N_c N_v} e^{\frac{-E_g}{2kT}} \right)^2$$

$$= 5.65 \cdot 10^{23} / \text{cm}^6$$

n (/cm ³)	p (/cm ³)	np (/cm ⁶)
10^{16}	$5.9 \cdot 10^7$	$5.9 \cdot 10^{23}$
10^{18}	$1.2 \cdot 10^5$	$1.2 \cdot 10^{23}$
10^{19}	245	$245 \cdot 10^{19}$

Thus the mass action law is valid only when the Maxwell-Boltzmann approximation is valid.

2. The Fermi-Dirac integral can be calculated by substituting $j = -0.5, 0, 0.5$ for 1D, 2D and 3D systems. Taking GaAs ($m^* = 0.067m_0$) as an example and assuming $E_f - E_c = 0.1$ eV, the carrier concentrations can be calculated using the following equations:

$$F_j(\eta_F) = \eta_F^{j+1} / \Gamma(j+2)$$

$$n_{1D} = \frac{\sqrt{2m^*kT}}{h\sqrt{\pi}} F_{-\frac{1}{2}}(\eta_F)$$

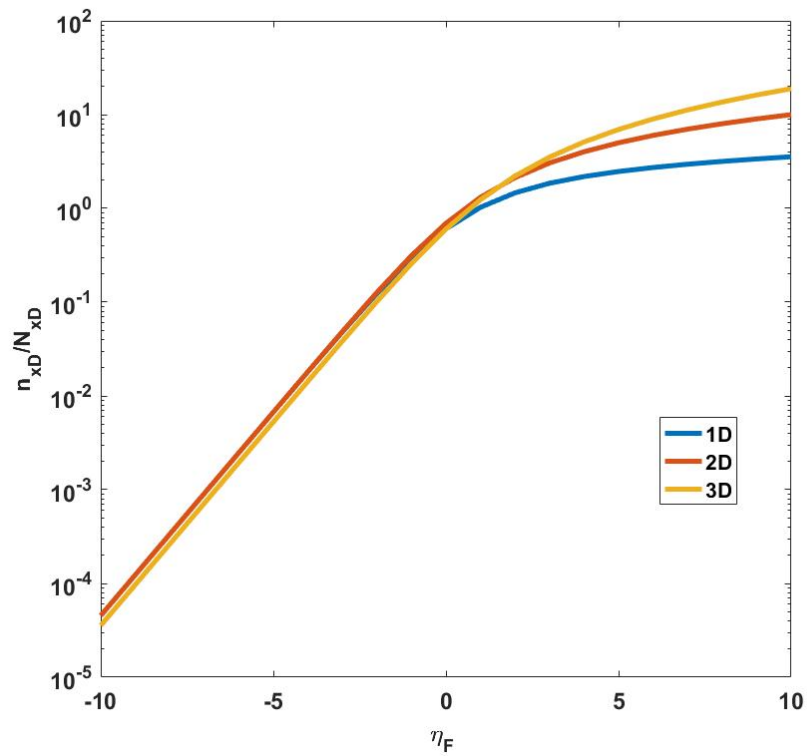
$$= 28 \text{ cm}^{-3}$$

$$n_{2D} = \left(\frac{m^*kT}{\pi h^2} \right) F_0(\eta_F)$$

$$= 7 \cdot 10^8 \text{ cm}^{-3}$$

$$n_{3D} = 2 \left(\frac{2\pi m^*kT}{h^2} \right)^{1.5} F_{\frac{1}{2}}(\eta_F)$$

$$= 4 \cdot 10^{18} \text{ cm}^{-3}$$



$$3. \quad n_s = \int_{E_1}^{\infty} D_{2D} f_0(E, E_f) dE$$

For low temperature, the effective density of states reduces and hence Maxwell-Boltzmann condition ($n < 0.05 N_c$) is not valid. Hence considering degeneracy,

$$\begin{aligned} &= \int_{E_1}^{\infty} D_{2D} (1 - \theta(E_f)) dE \\ &= \int_{E_1}^{E_f} D_{2D} dE \\ &= \frac{m^*}{\pi h^2} (E_f - E_1) \\ E_f - E_1 &= \frac{\pi h^2}{m^*} n_s \end{aligned}$$

	$m^* (m_0)$	$E_f - E_1$ (eV)
InAs	0.026	0.28
GaAs	0.067	0.11
$\text{In}_{0.53}\text{Ga}_{0.47}\text{As}$	0.041	0.18

4. To avoid short channel effects,

$$L_g > 2\lambda$$

$$L_g > 2*(t_{QW} + 2t_{ox}) \text{ [since the dielectric constants are assumed to be equal]}$$

$$t_{QW} < (L_g - 4t_{ox})/2$$

Thus the thickest possible quantum well to avoid short channel effects with the given $t_{ox} = 2\text{nm}$ and $L_g = 10\text{nm}$ is $t_{QW} = 1\text{nm}$.

5. a) Oxide capacitance $C_{ox} = \frac{\epsilon_{ox}\epsilon_0}{t_{ox}} = 0.089 \text{ F/m}^2$

b) Quantum capacitance $C_q = \frac{q^2 m^*}{\pi h^2} = 0.027 \text{ F/m}^2$

c) Charge centroid capacitance $C_c = \frac{\epsilon_s \epsilon_0}{0.36 * t_{well}} = 0.068 \text{ F/m}^2$

Total gate capacitance $C_g = \frac{1}{C_{ox}^{-1} + C_q^{-1} + C_c^{-1}} = 0.016 \text{ F/m}^2$

6. a) Ignore C_c

$$C_g = \frac{1}{C_{ox}^{-1} + C_q^{-1}} = \frac{\epsilon_{ox}\epsilon_0}{t_{ox} + \Delta t_{ox}}$$

$$\Delta t_{ox} = \frac{\epsilon_{ox}\epsilon_0 \pi h^2}{q^2 m^*}$$

b-d) $C_g/C_{ox} = \frac{1}{1 + \left(\frac{\Delta t_{ox}}{t_{ox}}\right)}$

Larger C_g/C_{ox} signifies $C_q > C_{ox}$. From the plots, GaN with larger m^* than InAs has higher C_g/C_{ox} even for thinner t_{ox} and so the gate stack is more scalable for GaN.

